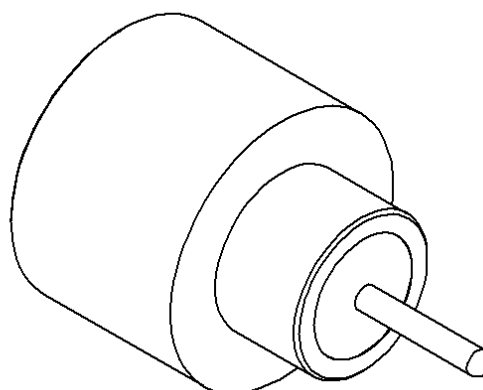
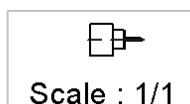
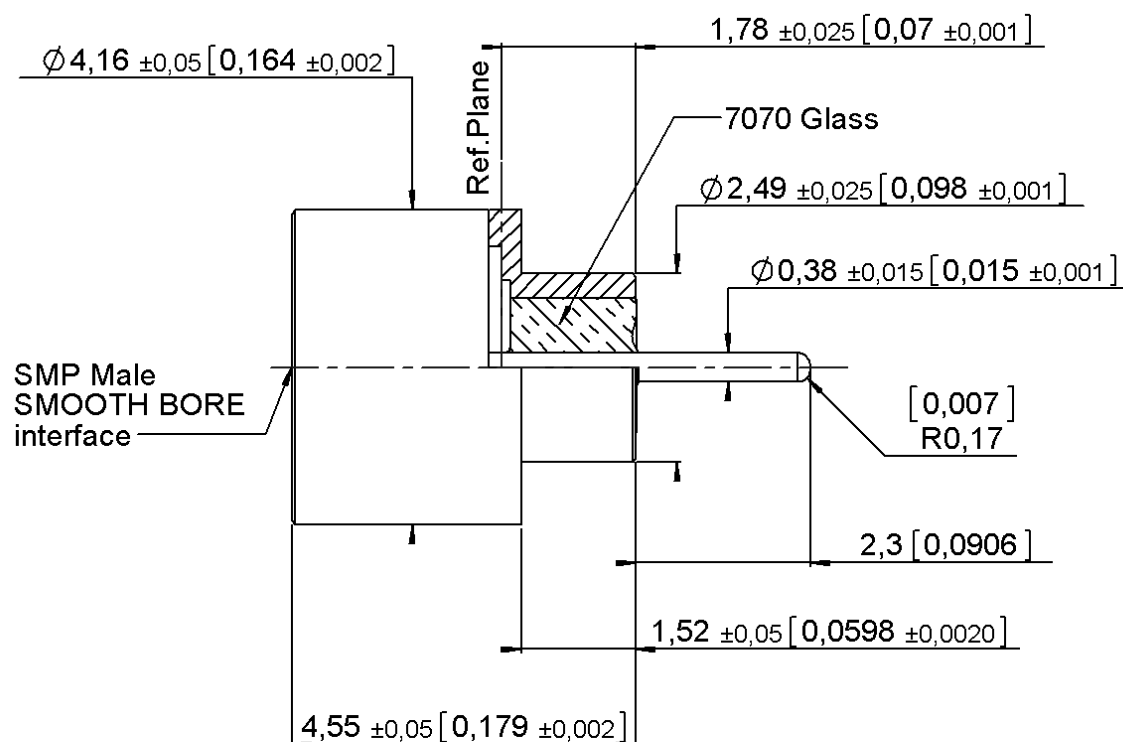


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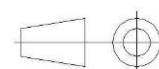
ISSUE 18-02-16A

SERIES SMP

PART NUMBER R222645750



All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	DILVER P1	GOLD OVER NICKEL
Center contact	DILVER P1	GOLD 0.5 OVER NICKEL 2
Outer contact		
Insulator	GLASS	
Gasket		
Others parts		
-	-	-
-	-	-

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SERIES SMP

PART NUMBER R222645750

PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-40	GHz
VSWR	1.15* +	0,0000	x F(GHz) Maxi
Insertion loss		0.12	√F(GHz) dB Maxi
RF leakage	- (NA	- F(GHz) dB Maxi
Voltage rating		335	Veff Maxi
Dielectric withstanding voltage		500	Veff mini
Insulation resistance		5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		6.7	N mini
Axial force – Opposite end		6.7	N mini
Torque		NA	N.cm mini
Recommended torque			
Mating		NA	N.cm
Panel nut		NA	N.cm
Mating life		1000	Cycles mini
Weight		0,1700	g

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	10-8	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

OTHER CHARACTERISTICS

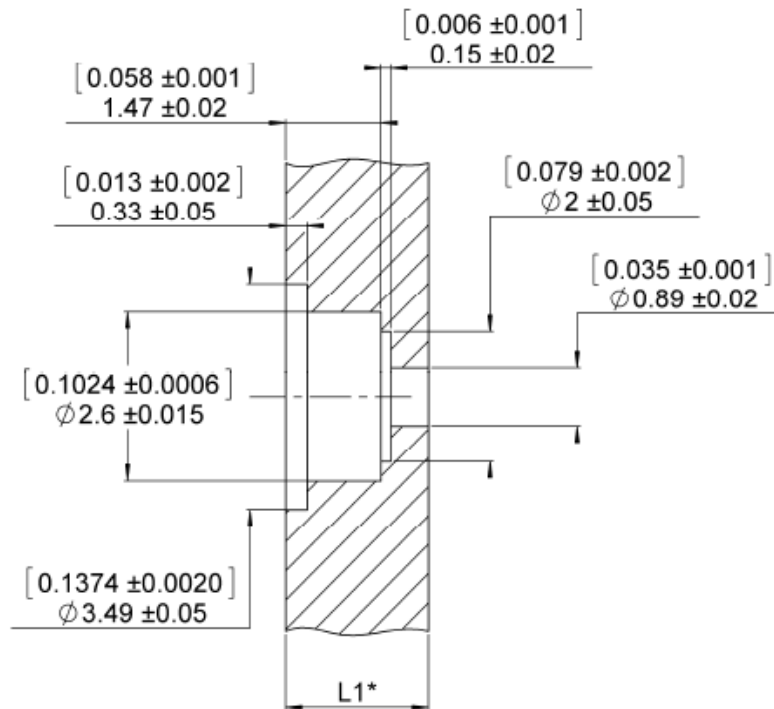
Assembly instruction:

Others:

* to 18 GHz

Customer code: G0080199

RECOMMENDED MOUNTING HOLE



*L1 dimension have to be determined according to each application

Solder procedure

1. Degrease and clean connector and box
2. Solder the connector on the panel. We advise SnAg4 Cu0.5, we recommend a low residue flux. Preheating at 100 °C during solder operation.
3. Solder the pin on the track. We advise SnAg4 Cu0.5, we recommend a low residue flux. Preheating at 100 °C (only for the ceramic substrate). Take care not to exceed 260°C during solder operation